TPS22916xx 1V 至 5.5V、2A 60mΩ 超低泄漏负载开关

1 特性

- 输入电压范围 (V_{IN})：1 V 至 5.5V
- 最大持续电流 (I_{MAX})：2A
- 导通电阻 (R_{ON})：
  - 5V V_{IN} = 60mΩ（典型值）、100mΩ（85°C 最大值）
  - 1.8V V_{IN} = 100mΩ（典型值）、150mΩ（85°C 最大值）
  - 1V V_{IN} = 200mΩ（典型值）、325mΩ（85°C 最大值）
- 超低功耗：
  - 导通状态 (I_Q)：0.5μA（典型值）、1μA（最大值）
  - 关闭状态 (I_{SD})：10nA（典型值）、100nA（最大值）
  - TPS22916BL/CL/CNL (I_{SD})：100nA（典型值）、300nA（最大值）
- ON 引脚智能下拉电阻 (R_{PD})：
  - ON ≥ V_{IH} (I_{ON})：10nA（最大值）
  - ON ≤ V_{IL} (R_{PD})：750kΩ（典型值）
- C 版本的慢时序可限制浪涌电流：
  - 5V 开通时间 (t_{ON})：5mV/μs 时为 1400μs
  - 1.8V 开通时间 (t_{ON})：1mV/μs 时为 3000μs
  - 1V 开通时间 (t_{ON})：0.3mV/μs 时为 6500μs
- B 版本的快速时序可减少等待时间：
  - 5V 开通时间 (t_{ON})：57mV/μs 时为 115μs
  - 1.8V 开通时间 (t_{ON})：12mV/μs 时为 250μs
  - 1V 开通时间 (t_{ON})：3.3mV/μs 时为 510μs
- 常开的真反向电流阻断 (RCB)：
  - 激活电流 (I_{RCB})：–500mA（典型值）
  - 反向泄漏电流 ($I_{IN,RCB}$)：–300nA（最大值）
- 快速输出放电 (QOD)：150Ω（典型值）（N 版本无 QOD）
- 低电平有效使能选项（L 版本）

2 应用

- 可穿戴
- 智能电话
- 平板电脑
- 便携式扬声器

3 说明

TPS22916xx 是一款小型单通道负载开关，采用低漏电 P 沟道 MOSFET 实现最小的功率损耗。高级栅极控制设计支持低至 1V 的工作电压，且增加超小的导通电阻和功率损耗。

多个时序选项可支持各种系统负载条件。对于高容性负载，C 版本的慢速导通时序可更大限度减小浪涌电流。而在低容性负载中，B 版本的快速时序可减少所需的等待时间。

开关导通状态由数字输入控制，此输入可与低压控制信号直接连接。此器件同时提供高电平有效和低电平有效 (L) 版本。首次加电时，此器件使用智能下拉电阻来保持 ON 引脚不悬空，直到系统时序控制完成。ON 引脚故意驱动为高电平 (≥V_{IH}) 后，便会断开智能下拉电阻，从而防止不必要的功率损耗。

TPS22916xx 采用节省空间的小型 0.78mm × 0.78mm、0.4mm 间距、0.5mm 高度的 4 引脚晶圆芯片级 (WCSP) 封装 (YFP)。此器件的工作温度范围为 –40°C 至 +85°C。

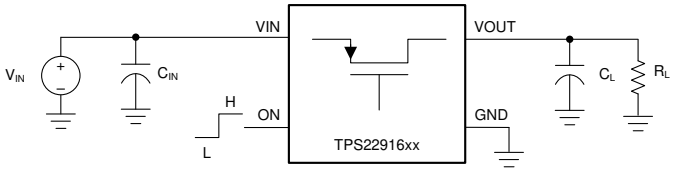
器件信息(1)

器件型号	封装	封装尺寸（标称值）
TPS22916xx	WCSP (4)	0.78mm × 0.78mm

(1) 如需了解所有可用封装，请参阅产品说明书末尾的可订购产品附录。

器件比较表

版本	时序	QOD	使能 (ON)
TPS22916B	快	是	高电平有效
TPS22916BL	快	是	低电平有效
TPS22916C	慢	是	高电平有效
TPS22916CN	慢	否	高电平有效
TPS22916CL	慢	是	低电平有效
TPS22916CNL	慢	否	低电平有效



简化版原理图

Table of Contents

4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision E (September 2020) to Revision F (December 2021) **Page**

- 向数据表添加了 TPS22916CNL 和 TPS22916BL 可订购产品 1

Changes from Revision D (October 2019) to Revision E (September 2020) **Page**

- 更新了整个文档中的表格、图和交叉参考的编号格式 1

Changes from Revision C (October 2018) to Revision D (October 2019) **Page**

- 将封装尺寸从 0.74mm x 0.74mm 更改为 0.78mm x 0.78mm 1

Changes from Revision B (December 2017) to Revision C (October 2018) **Page**

- Changed Package Drawing Dimensions 21

Changes from Revision A (September 2017) to Revision B (December 2017) **Page**

- 更改了标记为激光打标的引脚图 1

Changes from Revision * (July 2017) to Revision A (September 2017) **Page**

- 将器件文档从“预告信息”更改为“量产数据” 1

5 Pin Configuration and Functions

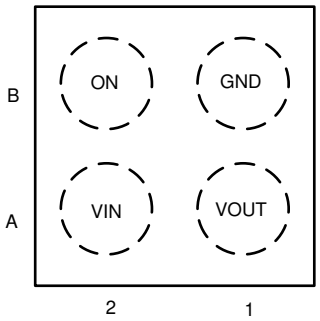


图 5-1. YFP Package 4-Pin WSON Laser Marking View

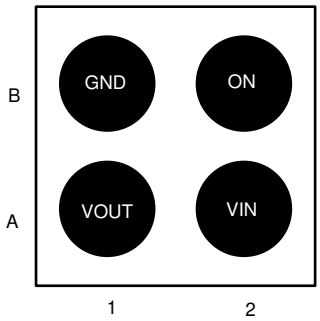


图 5-2. YFP Package 4-Pin WSON Bump View

表 5-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
A1	VOUT	Power	Switch output
A2	VIN	Power	Switch input
B1	GND	Ground	Device ground
B2	ON	Digital input	Device enable

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{IN}	Input voltage	– 0.3	6	V
V_{OUT}	Output voltage	– 0.3	6	V
V_{ON}	Enable voltage	– 0.3	6	V
I_{MAX}	Maximum continuous switch current		2	A
I_{PLS}	Maximum pulsed switch current, pulse < 300-µs, 2% duty cycle		2.5	A
$T_{J,MAX}$	Maximum junction temperature		125	°C
T_{STG}	Storage temperature	– 65	150	°C
T_{LEAD}	Maximum Lead temperature (10-s soldering time)		300	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions. Pins listed as ±2000 V may actually have higher performance.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions. Pins listed as ±500 V may actually have higher performance.

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{IN}	Input voltage	1	5.5	V
V_{OUT}	Output voltage	0	5.5	V
V_{IH}	High-level input voltage, ON	1	5.5	V
V_{IL}	Low-level input voltage, ON	0	0.35	V
T_A	Operating free-air temperature	– 40	85	°C

6.4 Thermal Information

Thermal Parameters(1)		TPS22916xx YFP (WCSP) 4 PINS	UNIT
θ_{JA}	Junction-to-ambient thermal resistance	193	°C/W
θ_{JCtop}	Junction-to-case (top) thermal resistance	2.3	°C/W
θ_{JB}	Junction-to-board thermal resistance	36	°C/W
ψ_{JT}	Junction-to-top characterization parameter	12	°C/W
ψ_{JB}	Junction-to-board characterization parameter	36	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics

Unless otherwise noted, the specification in the following table applies for all variants over the entire recommended power supply voltage range of 1 V to 5.5 V unless noted otherwise. Typical Values are at 25°C.

PARAMETER		TEST CONDITIONS		T_J	MIN	TYP	MAX	UNIT
INPUT SUPPLY (VIN)								
$I_{Q,VIN}$	V_{IN} Quiescent current	Enabled, V_{OUT} = Open		–40°C to +85°C		0.5	1.0	µA
$I_{SD,VIN}$	V_{IN} Shutdown current	Disabled, V_{OUT} = GND (TPS22916B/C/CN)		–40°C to +85°C		10	100	nA
		Disabled, V_{OUT} = GND (TPS22916BL/CL/CNL)		–40°C to +85°C		100	300	nA
ON-RESISTANCE (R_{ON})								
R_{ON}	ON-Resistance	I_{OUT} = 200 mA	V_{IN} = 5 V	25°C		60	80	mΩ
				–40°C to +85°C			100	
				–40°C to +105°C			120	
			V_{IN} = 3.6 V	25°C		70	90	
				–40°C to +85°C			120	
				–40°C to +105°C			140	
			V_{IN} = 1.8 V	25°C		100	125	
				–40°C to +85°C			150	
				–40°C to +105°C			175	
			V_{IN} = 1.2 V	25°C		150	200	
				–40°C to +85°C			250	
				–40°C to +105°C			300	
			V_{IN} = 1 V	25°C		200	275	
				–40°C to +85°C			325	
				–40°C to +105°C			375	
ENABLE PIN (ON)								
I_{ON}	ON Pin leakage	Enabled		–40°C to +85°C	–10		10	nA
R_{PD}	Smart Pull Down Resistance	Disabled		–40°C to +85°C		750		kΩ
REVERSE CURRENT BLOCKING (RCB)								
I_{RCB}	RCB Activation Current	Enabled, $V_{OUT} > V_{IN}$		–40°C to +85°C		-500		mA
t_{RCB}	RCB Activation time	Enabled, $V_{OUT} > V_{IN}$ + 200mV		–40°C to +85°C		10		µs
V_{RCB}	RCB Release Voltage	Enabled, $V_{OUT} > V_{IN}$		–40°C to +85°C		25		mV
$I_{IN,RCB}$	VIN Reverse Leakage Current	0 V ⩽ V_{IN} + V_{RCB} ⩽ V_{OUT} ⩽ 5.5 V		–40°C to +85°C			300	nA
QUICK OUTPUT DISCHARGE (QOD)								
QOD(1)	Output discharge resistance	Disabled (Not in TPS22916CN/CNL)		–40°C to +85°C		150		Ω

(1) For more information on which devices include quick output discharge, see the *Device Functional Modes* section.

6.6 Switching Characteristics

Unless otherwise noted, the typical characteristics in the following table applies over the entire recommended power supply voltage range of 1 V to 5.5 V at 25°C with a load of C_L = 0.1µF, R_L = 10Ω.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
TPS22916B, TPS22916BL						
t_{ON}	Turn On Time	V_{IN} = 5 V		115		µs
		V_{IN} = 3.6 V		140		
		V_{IN} = 1.8 V		250		
		V_{IN} = 1.2 V		350		
		V_{IN} = 1 V		510		
t_{RISE}	Rise Time	V_{IN} = 5 V		70		µs
		V_{IN} = 3.6 V		80		
		V_{IN} = 1.8 V		130		
		V_{IN} = 1.2 V		190		
		V_{IN} = 1 V		240		
SR_{ON}	Slew Rate	V_{IN} = 5 V		57		mV/µs
		V_{IN} = 3.6 V		36		
		V_{IN} = 1.8 V		12		
		V_{IN} = 1.2 V		5.1		
		V_{IN} = 1 V		3.3		
t_{OFF}	Turn Off Time	V_{IN} = 5 V		5		µs
		V_{IN} = 3.6 V		5		
		V_{IN} = 1.8 V		10		
		V_{IN} = 1.2 V		15		
		V_{IN} = 1 V		25		
t_{FALL}	Fall Time	C_L = 0.1 µF, R_L = 10 Ω(1)		2.3		µs
		C_L = 1µF, R_L = Open(1)		315		

6.6 Switching Characteristics (continued)

Unless otherwise noted, the typical characteristics in the following table applies over the entire recommended power supply voltage range of 1 V to 5.5 V at 25°C with a load of C_L = 0.1µF, R_L = 10Ω.

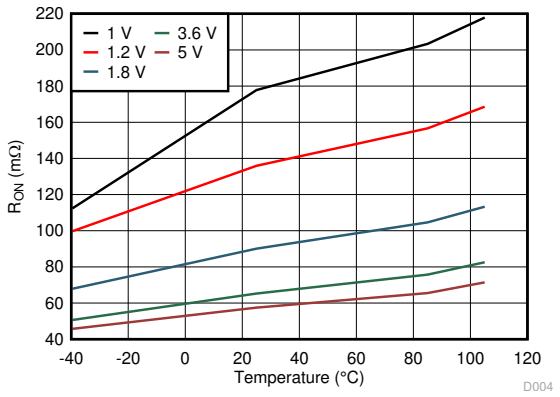
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
TPS22916C, TPS22916CN, TPS22916CL, TPS22916CNL						
t_{ON}	Turn On Time	V_{IN} = 5 V		1400		µs
		V_{IN} = 3.6 V		1700		
		V_{IN} = 1.8 V		3000		
		V_{IN} = 1.2 V		5000		
		V_{IN} = 1 V		6500		
t_{RISE}	Rise Time	V_{IN} = 5 V		800		µs
		V_{IN} = 3.6 V		900		
		V_{IN} = 1.8 V		1400		
		V_{IN} = 1.2 V		2300		
		V_{IN} = 1 V		3000		
SR_{ON}	Slew Rate	V_{IN} = 5 V		5		mV/µs
		V_{IN} = 3.6 V		3.2		
		V_{IN} = 1.8 V		1		
		V_{IN} = 1.2 V		0.4		
		V_{IN} = 1 V		0.3		
t_{OFF}	Turn Off Time	V_{IN} = 5 V		5		µs
		V_{IN} = 3.6 V		5		
		V_{IN} = 1.8 V		10		
		V_{IN} = 1.2 V		15		
		V_{IN} = 1 V		25		
t_{FALL}	Fall Time(2)	C_L = 0.1 µF, R_L = 10 Ω(1)		2.3		µs
		CL = 10µF, RL = Open(1)		3150		

(1) See the *Fall Time (t_{FALL}) and Quick Output Discharge (QOD)* section for information on how R_L and C_L affect Fall Time.
(2) Devices without Quick Output Discharge (QOD) may not discharge completely.

6.7 Typical Characteristics

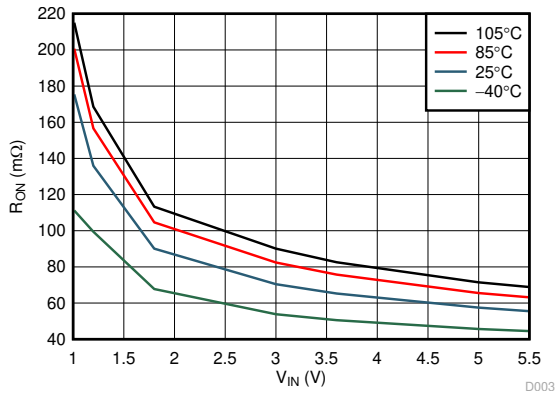
6.7.1 Typical Electrical Characteristics

The typical characteristics curves in this section apply to all devices unless otherwise noted.



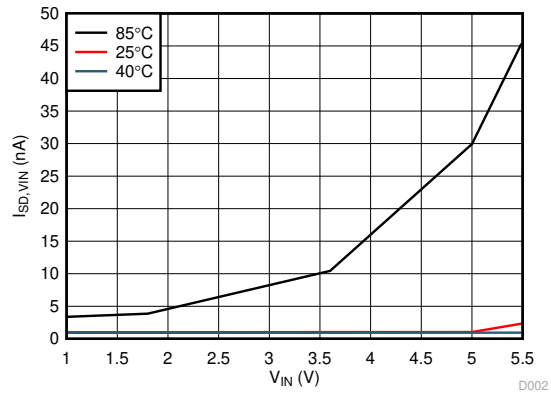
Enabled

图 6-1. ON-Resistance vs Temperature



Enabled

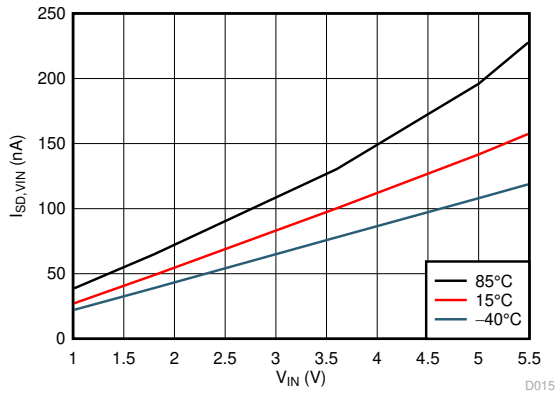
图 6-2. ON-Resistance vs Input voltage



TPS22916C, TPS22916CN, TPS22916B

$V_{ON} \leqslant V_{IL}$

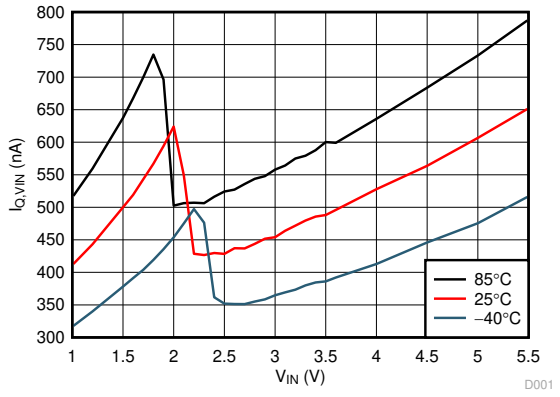
图 6-3. Shutdown Current



TPS22916CL, TPS22916BL, TPS22916CNL

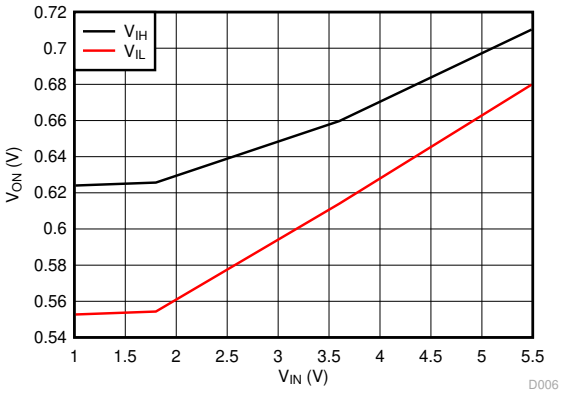
$V_{ON} \geqslant V_{IH}$

图 6-4. Shutdown Current (Active Low)



Enabled

图 6-5. Quiescent Current

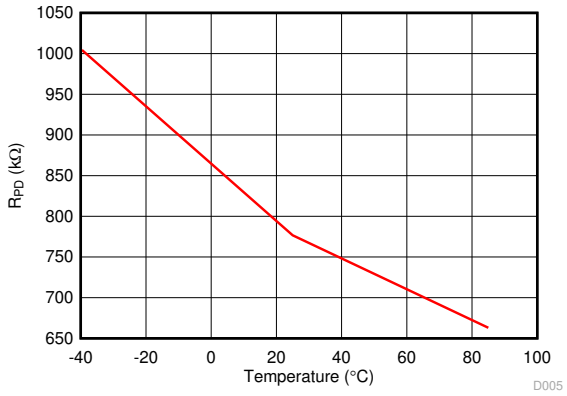


– 40°C to +85°C

图 6-6. ON Pin Threshold

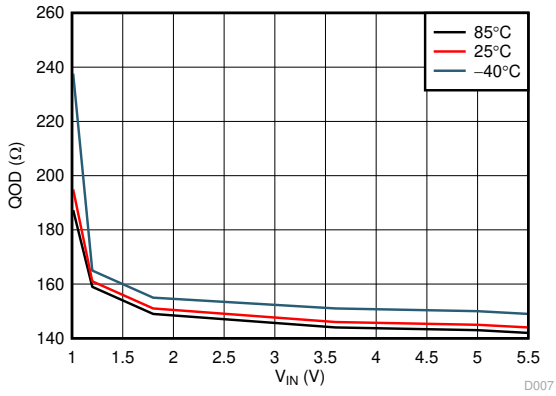
6.7.1 Typical Electrical Characteristics (continued)

The typical characteristics curves in this section apply to all devices unless otherwise noted.



$V_{ON} \leqslant V_{IL}$

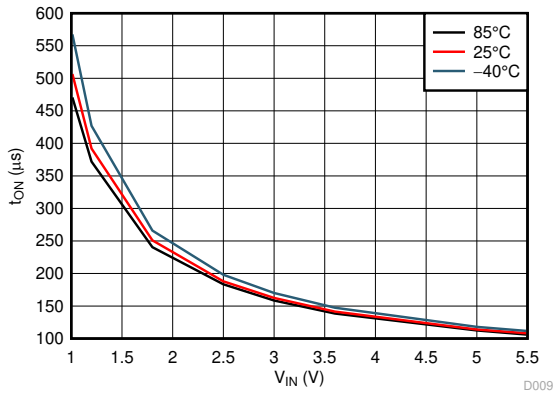
图 6-7. ON Pin Smart Pulldown



TPS22916C, TPS22916CL, TPS22916B, TPS22916BL

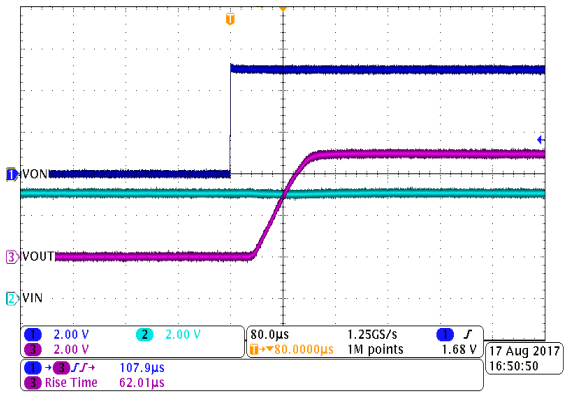
图 6-8. Quick Output Discharge

6.7.2 Typical Switching Characteristics



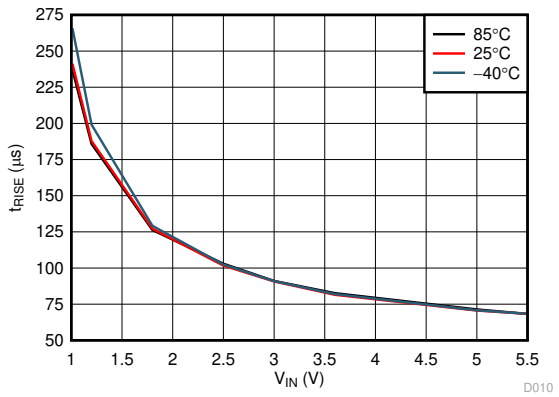
C_L = 0.1 µF R_L = 10 Ω

图 6-9. Fast Turn-On Time



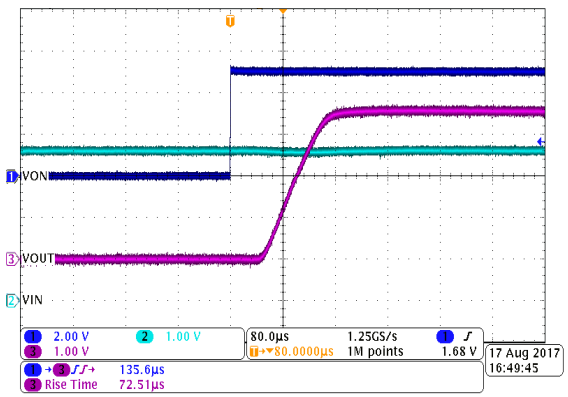
TPS22916B V_{IN} = 5 V C_L = 0.1 µF R_L = 10 Ω

图 6-10. Fast Turn-On at 5 V



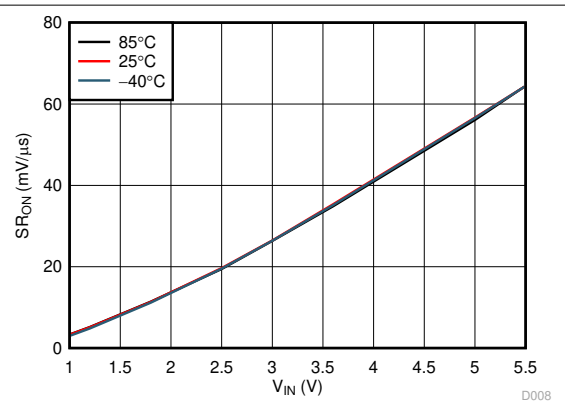
C_L = 0.1 µF R_L = 10 Ω

图 6-11. Fast Rise Time



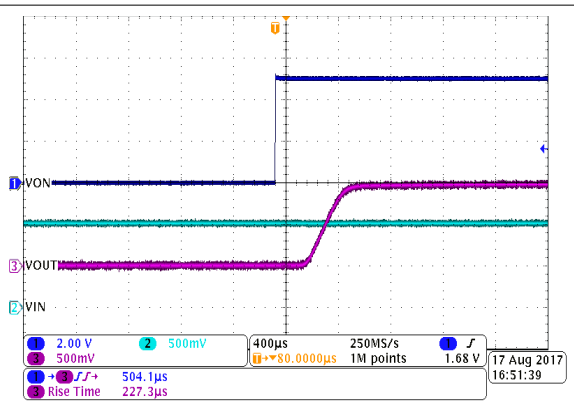
TPS22916B V_{IN} = 3.6 V C_L = 0.1 µF R_L = 10 Ω

图 6-12. Fast Turn-On at 3.6 V



C_L = 0.1 µF R_L = 10 Ω

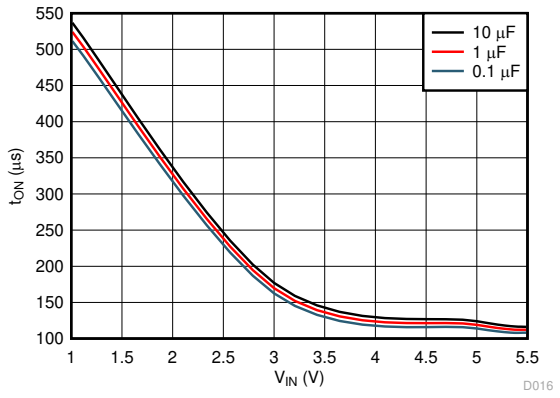
图 6-13. Fast Slew Rate



TPS22916B V_{IN} = 1 V C_L = 0.1 µF R_L = 10 Ω

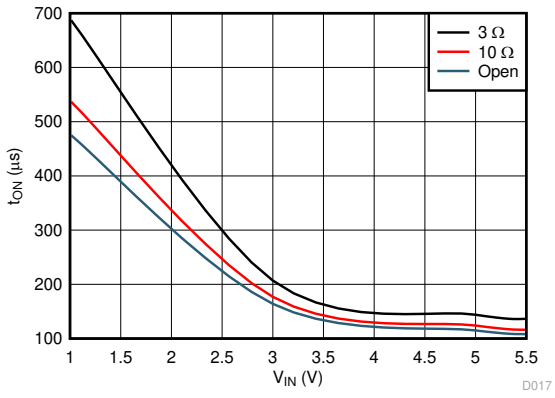
图 6-14. Fast Turn-On at 1 V

6.7.2 Typical Switching Characteristics (continued)



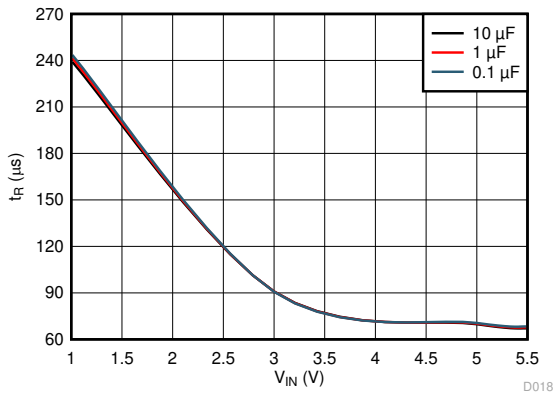
R_L = 10 Ω TPS22916B

图 6-15. Fast Turn-On vs Load Capacitance



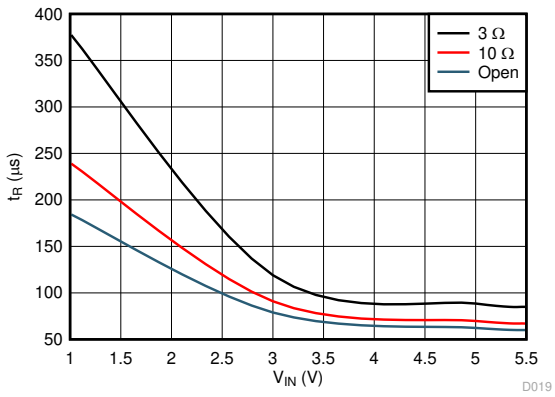
C_L = 10 µF TPS22916B

图 6-16. Fast Turn-On vs Load Resistance



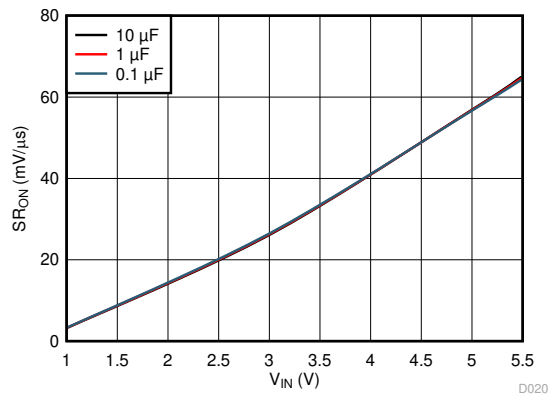
R_L = 10 Ω TPS22916B

图 6-17. Fast Rise Time vs Load Capacitance



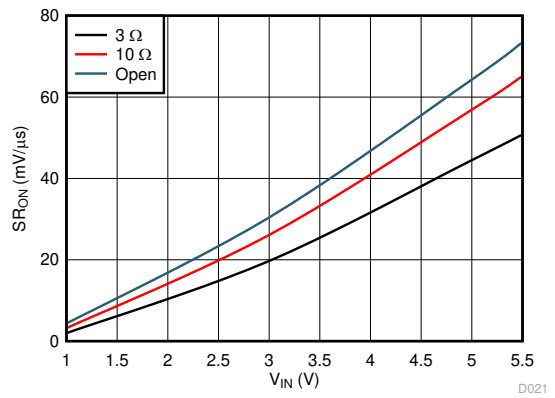
C_L = 10 µF TPS22916B

图 6-18. Fast Rise Time vs Load Resistance



R_L = 10 Ω TPS22916B

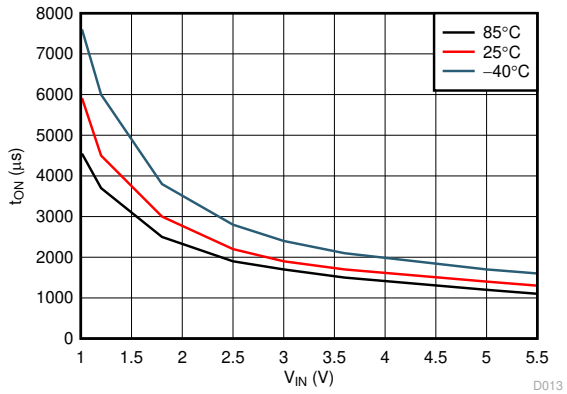
图 6-19. Fast Slew Rate vs Load Capacitance



C_L = 10 µF TPS22916B

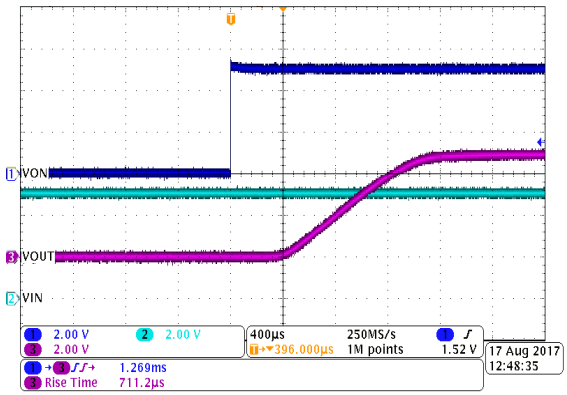
图 6-20. Fast Slew Rate vs Load Resistance

6.7.2 Typical Switching Characteristics (continued)



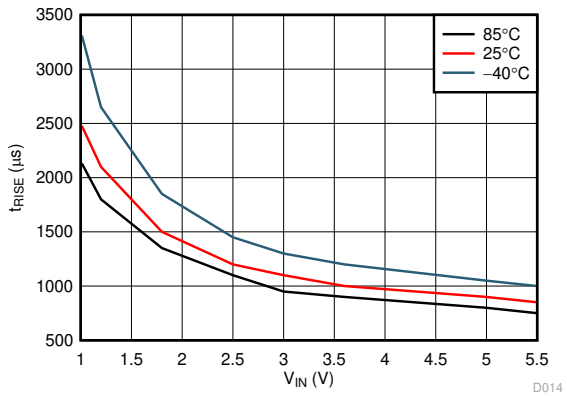
C_L = 0.1 µF R_L = 10 Ω

图 6-21. Slow Turn-On Time



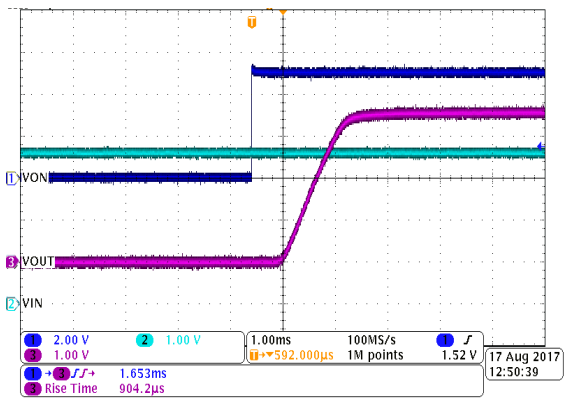
TPS22916C V_{IN} = 5 V C_L = 0.1 µF R_L = 10 Ω

图 6-22. Slow Turn-On at 5 V



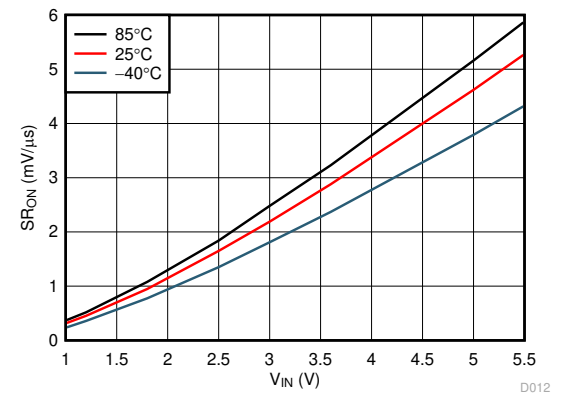
C_L = 0.1 µF R_L = 10 Ω

图 6-23. Slow Rise Time



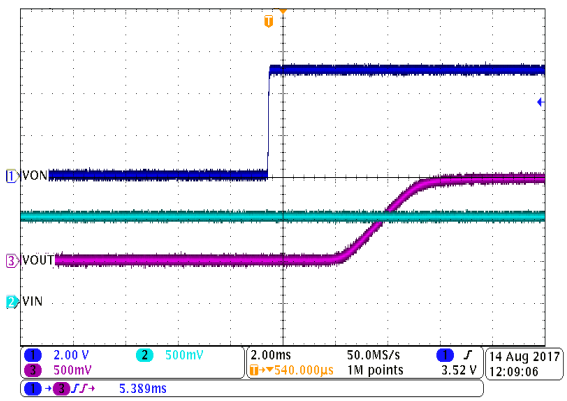
TPS22916C V_{IN} = 3.6 V C_L = 0.1 µF R_L = 10 Ω

图 6-24. Slow Turn-On at 3.6 V



C_L = 0.1 µF R_L = 10 Ω

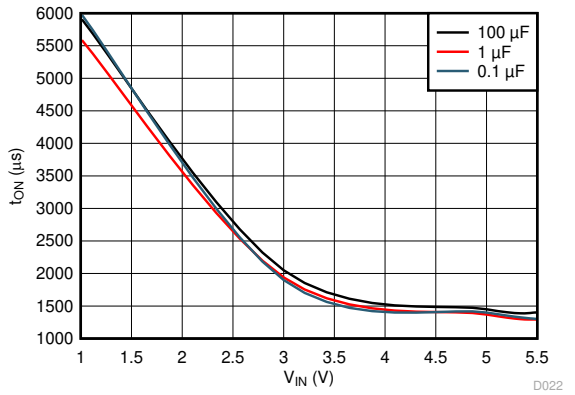
图 6-25. Slow Slew Rate



TPS22916C V_{IN} = 1 V C_L = 0.1 µF R_L = 10 Ω

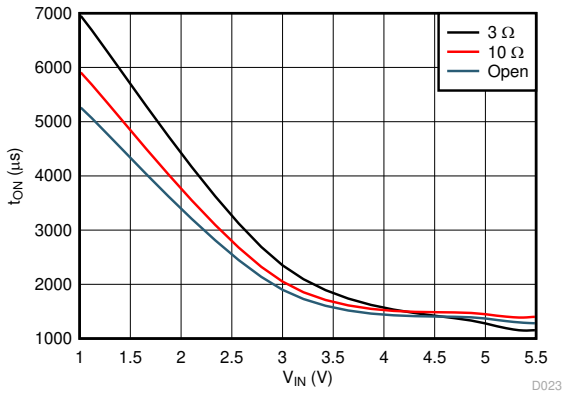
图 6-26. Slow Turn-On at 1 V

6.7.2 Typical Switching Characteristics (continued)



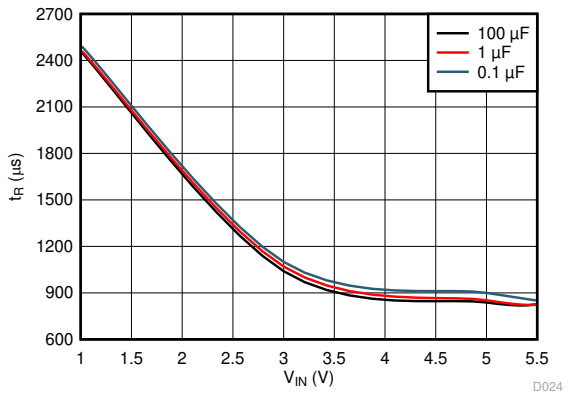
R_L = 10 Ω TPS22916C TPS22916CN TPS22916CL

图 6-27. Slow Turn-On vs Load Capacitance



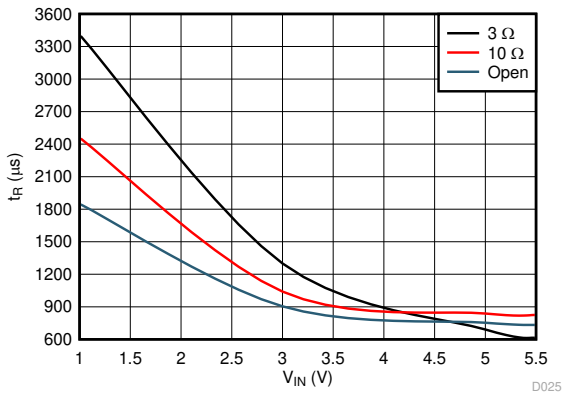
C_L = 100 µF TPS22916C TPS22916CN TPS22916CL

图 6-28. Slow Turn-On vs Load Resistance



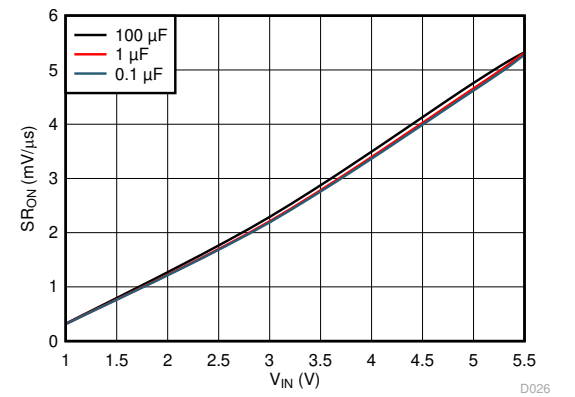
R_L = 10 Ω TPS22916C TPS22916CN TPS22916CL

图 6-29. Slow Rise Time vs Load Capacitance



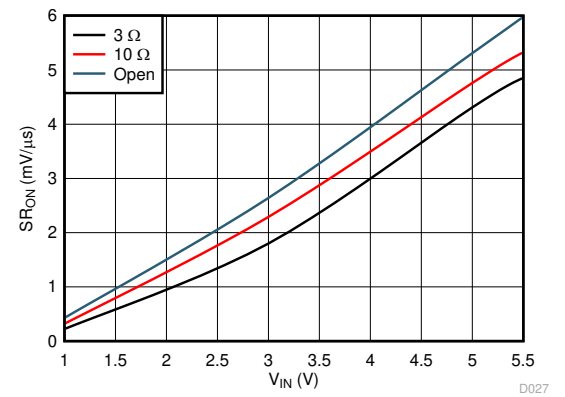
C_L = 100 µF TPS22916C TPS22916CN TPS22916CL

图 6-30. Slow Rise Time vs Load Resistance



R_L = 10 Ω TPS22916C TPS22916CN TPS22916CL

图 6-31. Slow Slew Rate vs Load Capacitance



C_L = 100 µF TPS22916C TPS22916CN TPS22916CL

图 6-32. Slow Slew Rate vs Load Resistance

6.7.2 Typical Switching Characteristics (continued)

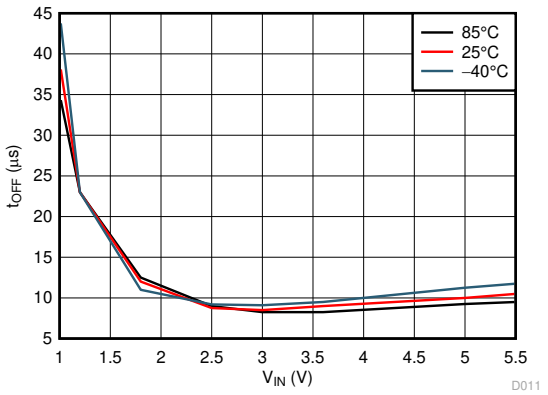
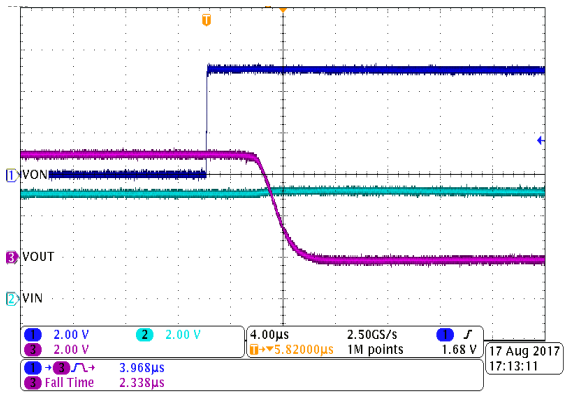
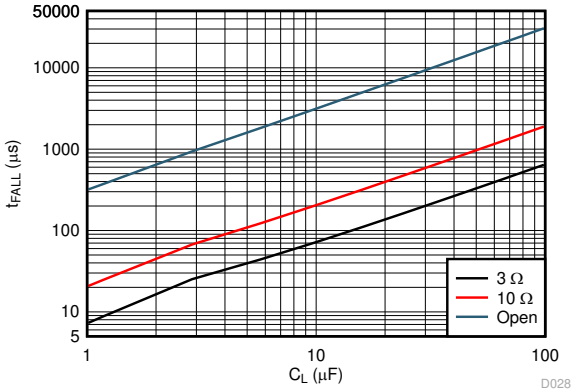


图 6-33. Turn-Off Time



TPS22916CL V_{IN} = 5 V C_L = 0.1 µF R_L = 10 Ω

图 6-34. Turn-Off at 5 V (Active Low)



V_{IN} = 1 V to 5.5 V TPS22916C TPS22916CL TPS22916B

图 6-35. Fall Time

7 Parameter Measurement Information

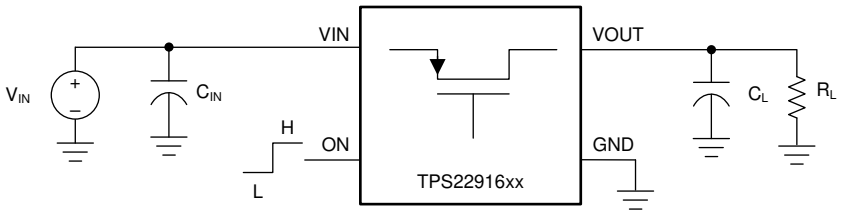


图 7-1. TPS22916 Test Circuit

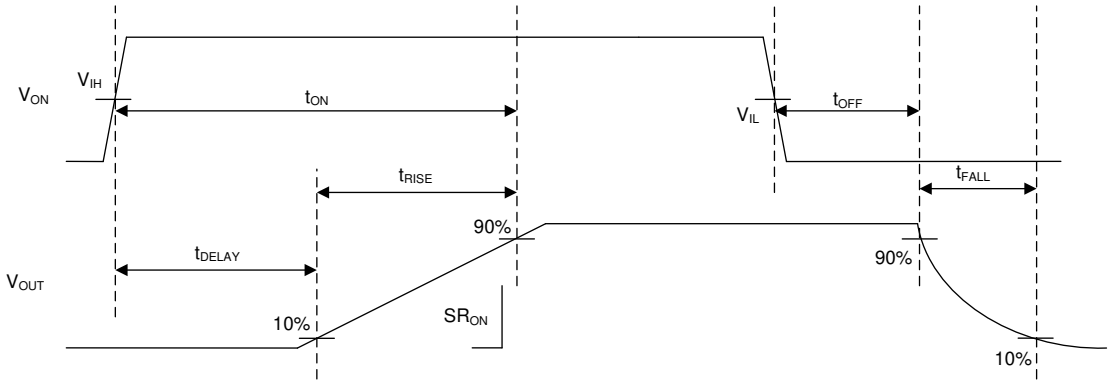


图 7-2. TPS22916 Timing Waveform

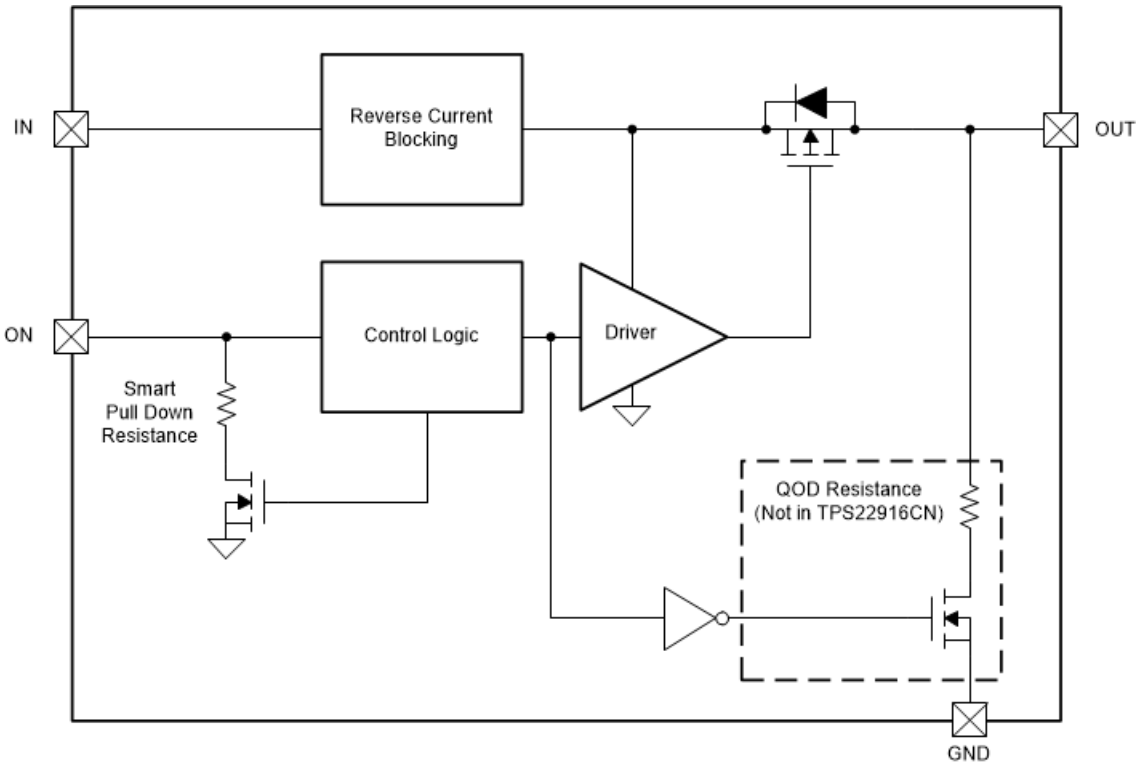
8 Detailed Description

8.1 Overview

This family of devices are single channel, 2-A load switches in ultra-small, space saving 4-pin WCSP package. These devices implement a low resistance P-channel MOSFET with a controlled rise time for applications that must limit inrush current.

These devices are designed to have very low leakage current during OFF state. This design prevents downstream circuits from pulling high standby current from the supply. Integrated control logic, driver, power supply, and output discharge FET eliminates the need for additional external components, which reduces solution size and BOM count.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 On and Off Control

The ON pin controls the state of the switch. The ON pin is compatible with standard GPIO logic threshold. the pin can be used with any microcontroller with 1.2-V, 1.8-V, 2.5-V, 3.3-V, or 5.5-V GPIO.

8.3.2 Fall Time (t_{FALL}) and Quick Output Discharge (QOD)

The TPS22916B, TPS22916BL, TPS22916C, and TPS22916CL include a Quick Output Discharge feature. When the switch is disabled, a discharge resistor is connected between VOUT and GND. This resistor has a typical value of QOD and prevents the output from floating while the switch is disabled.

As load capacitance and load resistance increase: t_{FALL} increases. The larger the load resistance or load capacitance is, the longer it takes to discharge the capacitor, resulting in a longer fall time.

The output fall time is determined by how quickly the load capacitance is discharged and can be found using 方程式 1 .

$$t_{FALL} = - (R_{DIS}) \times C_L \times \ln (V_{10\%} / V_{90\%}) \quad (1)$$

Where

- $V_{10\%}$ is 10% of the initial output voltage
- $V_{90\%}$ is 90% of the initial output voltage
- R_{DIS} is the result of the QOD resistance in parallel with the Load Resistance R_L
- C_L is the load capacitance

With the Quick Output Discharge feature, the QOD resistance is in parallel with R_L. This provides a lower total load resistance as seen from the load capacitance which discharges the capacitance faster resulting in a smaller t_{FALL}.

8.3.3 Full-Time Reverse Current Blocking

In a scenario where the device is enabled and V_{OUT} is greater than V_{IN} there is potential for reverse current to flow through the pass FET or the body diode. When the reverse current threshold (I_{RCB}) is exceeded, the switch is disabled within t_{RCB}. The switch remains off and block reverse current as long as the reverse voltage condition exists. After V_{OUT} has dropped below the V_{RCB} release threshold the TPS22916xx turns back on with slew rate control.

8.4 Device Functional Modes

表 8-1 describes the state for each variant as determined by the ON pin.

表 8-1. Device Function Table

ON	TPS22916B	TPS22916BL	TPS22916C	TPS22916CN	TPS22916CL	TPS22916CNL
$\leqslant V_{IL}$	Disabled	Enabled	Disabled	Disabled	Enabled	Enabled
$\geqslant V_{IH}$	Enabled	Disabled	Enabled	Enabled	Disabled	Disabled

表 8-2 shows when QOD is active for each variant.

表 8-2. QOD Function Table

Device	TPS22916B	TPS22916BL	TPS22916C	TPS22916CN	TPS22916CL	TPS22916CNL
Enabled	No	No	No	No	No	No
Disabled	Yes	Yes	Yes	No	Yes	No

表 8-3 shows when the ON pin smart pulldown is active.

表 8-3. Smart-ON Pulldown

V_{ON}	Pulldown
$\leqslant V_{IL}$	Connected
$\geqslant V_{IH}$	Disconnected

9 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客 户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Application Information

This section highlights some of the design considerations when implementing this device in various applications. A PSPICE model for this device is also available in the product page of this device.

9.2 Typical Application

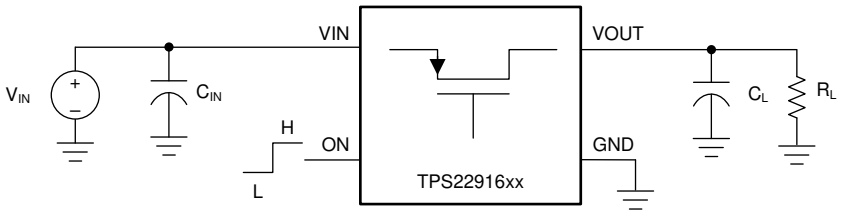


图 9-1. Typical Application

9.2.1 Design Requirements

For this design example, below, use the input parameters shown in 表 9-1.

表 9-1. Design Parameters

Design Parameter	Example Value
Input voltage (V_{IN})	3.6 V
Load capacitance (C_L)	47 µF
Maximum inrush current (I_{RUSH})	300 mA

9.2.2 Detailed Design Procedure

9.2.2.1 Maximum Inrush Current

When the switch is enabled, the output capacitors must be charged up from 0 V to VIN voltage. This charge arrives in the form of inrush current. Inrush current can be calculated using the following equation:

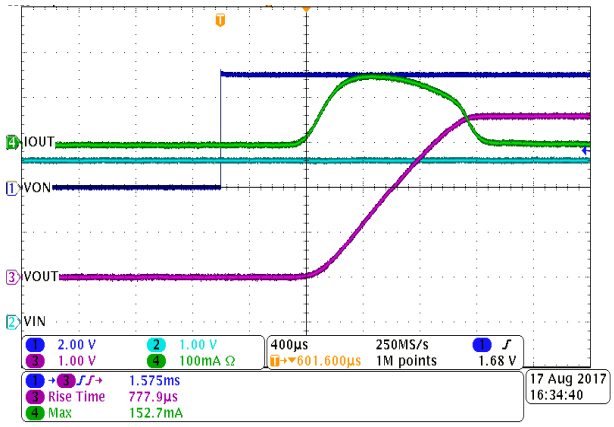
$$I_{RUSH} = C_L \times SR_{ON} \quad (2)$$

$$I_{RUSH} = 47\ \mu F \times 3.2\ mV/\mu s \quad (3)$$

$$I_{RUSH} = 150\ mA \quad (4)$$

The TPS22916x offers multiple rise time options to control the inrush current during turn-on. The appropriate device can be selected based upon the maximum acceptable slew rate which can be calculated using the design requirements and the inrush current equation. In this case, the TPS22916C provides a slew rate slow enough to limit the inrush current to the desired amount.

9.2.3 Application Curve



V_{IN} = 3.6 V C_L = 47 µF R_L = Open
TPS22916C T_A = 25°C

图 9-2. Inrush Current

10 Power Supply Recommendations

The device is designed to operate with a VIN range of 1 V to 5.5 V. The VIN power supply must be well regulated and placed as close to the device terminal as possible. The power supply must be able to withstand all transient load current steps. In most situations, using an input capacitance (C_{IN}) of 1 µF is sufficient to prevent the supply voltage from dipping when the switch is turned on. In cases where the power supply is slow to respond to a large transient current or large load current step, additional bulk capacitance can be required on the input.

11 Layout

11.1 Layout Guidelines

For best performance, all traces must be as short as possible. To be most effective, the input and output capacitors must be placed close to the device to minimize the effects that parasitic trace inductances can have on normal operation. Using wide traces for VIN, VOUT, and GND helps minimize the parasitic electrical effects.

11.2 Layout Example

方程式 3 shows an example for these devices. Notice the connection to system ground between the V_{OUT} Bypass Capacitor ground and the GND pin of the load switch,. This connection creates a ground barrier which helps to reduce the ground noise seen by the device.

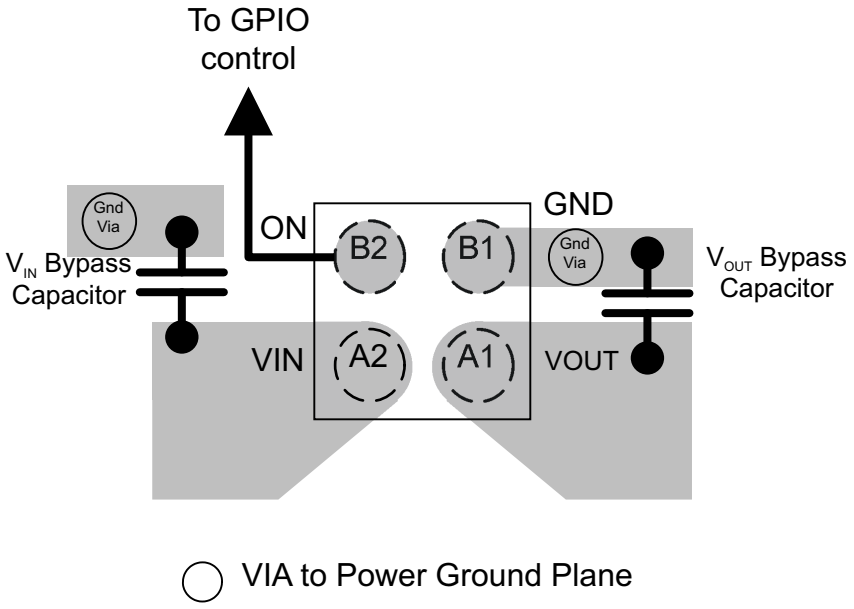


图 11-1. TPS22916xx Layout

11.3 Thermal Considerations

The maximum IC junction temperature must be restricted to 125°C under normal operating conditions. To calculate the maximum allowable dissipation, $P_{D(max)}$ for a given output current and ambient temperature, use 方程式 5 as a guideline:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_A}{R_{\theta JA}} \quad (5)$$

Where,

$P_{D(max)}$ = maximum allowable power dissipation

$T_{J(max)}$ = maximum allowable junction temperature

T_A = ambient temperature for the device

θ_{JA} = junction to air thermal impedance. See the *Thermal Information* section.

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

Texas Instruments, *TPS22916 Load Switch Evaluation Module* User's Guide

12.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

12.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

12.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

12.6 术语表

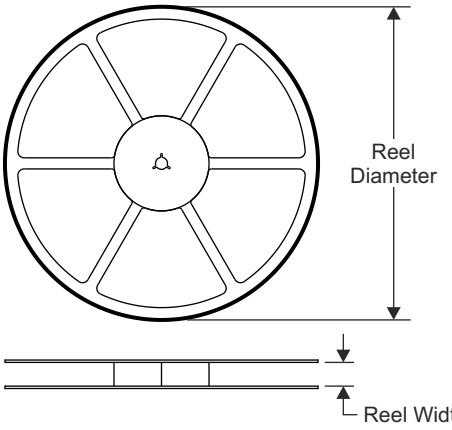
TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

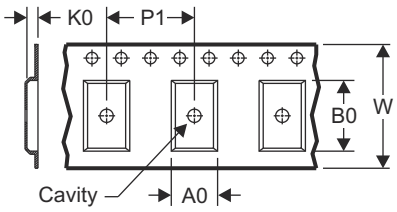
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

13.1 Tape and Reel Information

REEL DIMENSIONS

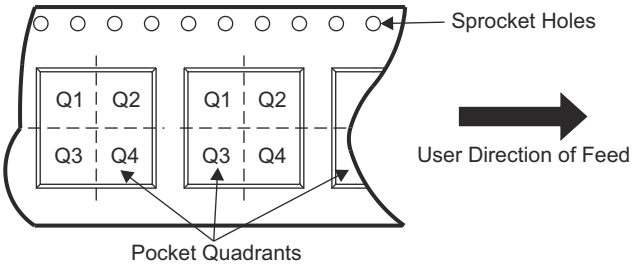


TAPE DIMENSIONS



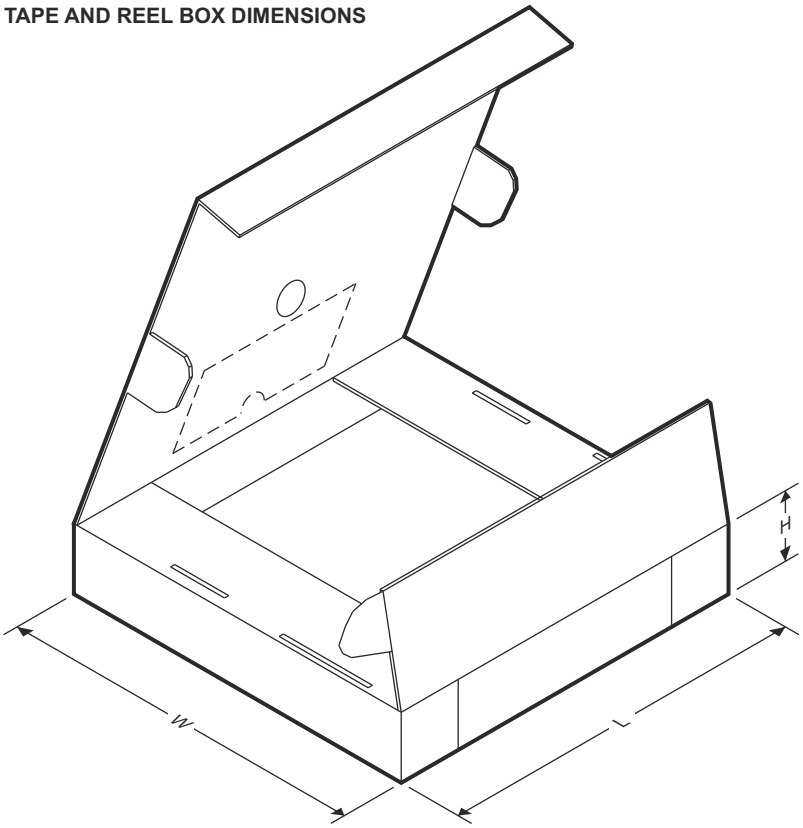
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS22916BYFPR	DSBGA	YFP	4	3000	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916BYFPT	DSBGA	YFP	4	250	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CLYFPR	DSBGA	YFP	4	3000	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CLYFPT	DSBGA	YFP	4	250	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CNYFPR	DSBGA	YFP	4	3000	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CNYFPT	DSBGA	YFP	4	250	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CYFPR	DSBGA	YFP	4	3000	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CYFPT	DSBGA	YFP	4	250	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916CNLYFPR	DSBGA	YFP	4	3000	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1
TPS22916BLYFPR	DSBGA	YFP	4	3000	180.0	8.4	0.86	0.86	0.59	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



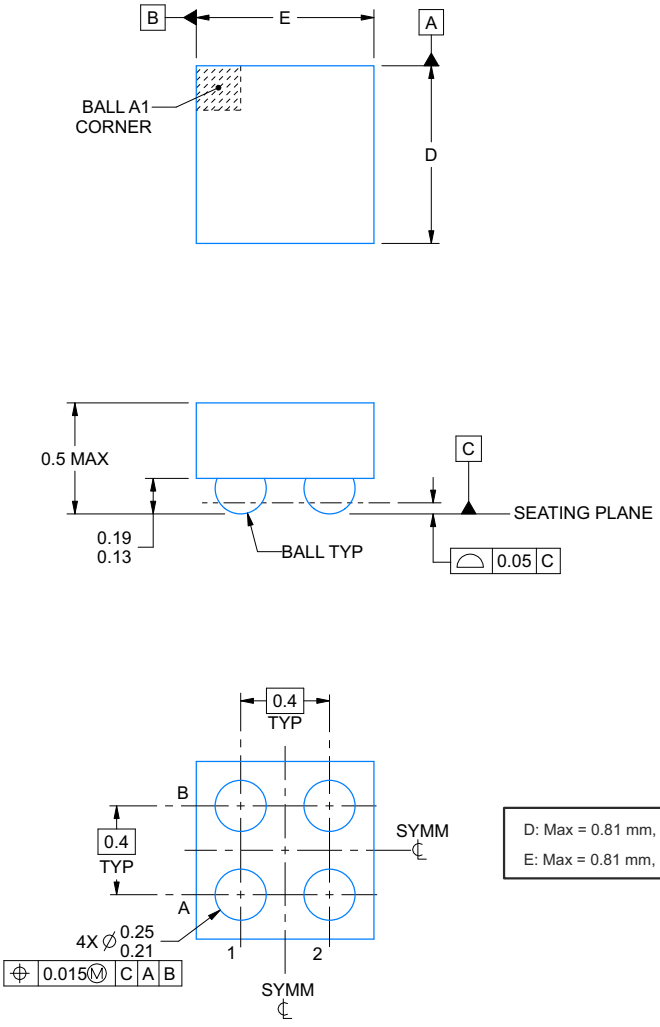
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS22916BYFPR	DSBGA	YFP	4	3000	182.0	182.0	20.0
TPS22916BYFPT	DSBGA	YFP	4	250	182.0	182.0	20.0
TPS22916CLYFPR	DSBGA	YFP	4	3000	182.0	182.0	20.0
TPS22916CLYFPT	DSBGA	YFP	4	250	182.0	182.0	20.0
TPS22916CNYFPR	DSBGA	YFP	4	3000	182.0	182.0	20.0
TPS22916CNYFPT	DSBGA	YFP	4	250	182.0	182.0	20.0
TPS22916CYFPR	DSBGA	YFP	4	3000	182.0	182.0	20.0
TPS22916CYFPT	DSBGA	YFP	4	250	182.0	182.0	20.0
TPS22916CNLYFPR	DSBGA	YFP	4	3000	182.0	182.0	20.0
TPS22916BLYFPR	DSBGA	YFP	4	3000	182.0	182.0	20.0

PACKAGE OUTLINE

YFP0004

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



NOTES:

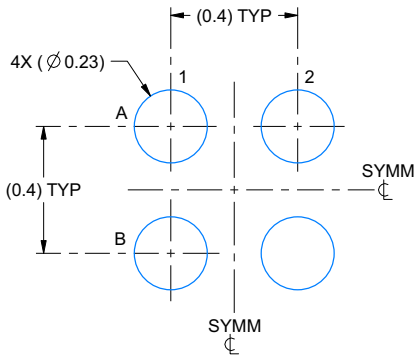
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

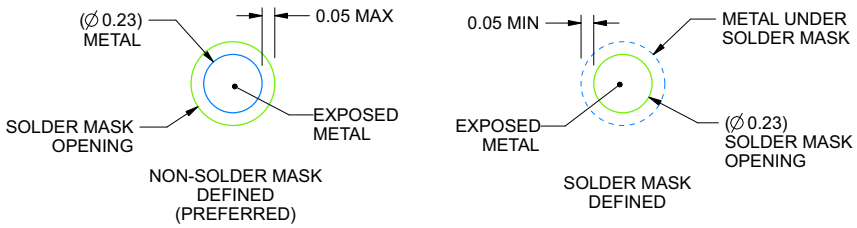
YFP0004

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:50X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

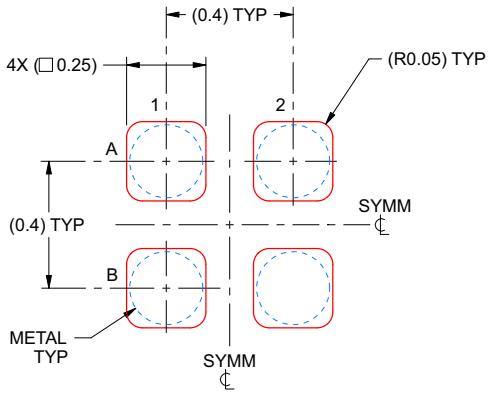
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YFP0004

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:50X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS22916BLYFPR	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	Q
TPS22916BLYFPR.A	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	Q
TPS22916BYFPR	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396 | SNAGCU	Level-1-260C-UNLIM	-40 to 85	(BA, R)
TPS22916BYFPR.A	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	(BA, R)
TPS22916BYFPT	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396 | SNAGCU	Level-1-260C-UNLIM	-40 to 85	(BA, R)
TPS22916BYFPT.A	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	(BA, R)
TPS22916CLYFPR	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B9
TPS22916CLYFPR.A	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B9
TPS22916CLYFPT	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B9
TPS22916CLYFPT.A	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B9
TPS22916CNLYFPR	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	S
TPS22916CNLYFPR.A	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	S
TPS22916CNYFPR	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B8
TPS22916CNYFPR.A	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B8
TPS22916CNYFPT	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B8
TPS22916CNYFPT.A	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B8
TPS22916CYFPR	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B7
TPS22916CYFPR.A	Active	Production	DSBGA (YFP) | 4	3000 | LARGE T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B7
TPS22916CYFPT	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B7
TPS22916CYFPT.A	Active	Production	DSBGA (YFP) | 4	250 | SMALL T&R	Yes	SAC396	Level-1-260C-UNLIM	-40 to 85	B7

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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